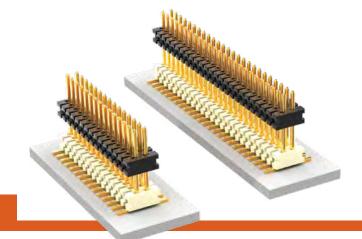


SMT MICRO BOARD HEADER

(1.00 mm) .0394" PITCH • MW SERIES



MW

Mates:

CLM, MLE

SPECIFICATIONS

Insulator Material: Top: Black LCP Bottom: Natural LCP Terminal Material: Phosphor Bronze Phosphor Bronze
Plating:
Au over 50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (02-30) (0.15 mm) .006" max (31-50)* *(.004" stencil solution may be available: contact IPG@samtec.com)





02 thru 50





-G

= 10 µ" (0.25 µm) Gold





-"XXX" = Stacker Height (in inches)

(2.41 mm) .095" to (6.22 mm) .245"

Example: -245 = (6.22 mm) .245"

-"XXX"

= Post Height (in inches)

(1.65 mm) .065" minimum

Example: -065 = (1.65 mm) .065"

POST HEIGHT OPTION

-A = Alignment Pin (5 positions minimum) Metal or plastic at Samtec's

discretion

-P = Pick & Place Pad (7 positions minimum)

-TR = Tape & Reel

-FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks)

No. of positions x (1.00) .03937 (3.18)

ALSO AVAILABLE MOQ Required

End shrouds End shrouds with guide posts



(7.87) .310 MAX OVERALL LENGTH (1.49)

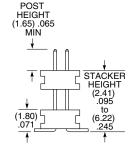


-P OPTION

APPLICATION

EXAMPLES		
LEAD STYLE		MATED
MW	CLM	HEIGHT*
-163-065	-02	(6.35 mm) .250"
-233-065		(8.13 mm) .320"

^{*}Processing conditions will affect mated height



Notes:

For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

This Series is non-standard, non-returnable.

(2.21)